



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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203 Series Fuse



Description

Fast-Acting and Slo-Blo® Fuse versions of the Flat-Pak® Fuse designs are available. Both designs are available in either a gull-wing surface mount package or a DIP configuration for through-hole mounting. These fuse designs feature a 250 VAC rating in a low profile, rectangular package.

Agency Approvals

AGENCY	AGENCY FILE NUMBER	AMPERE RANGE
	E10480	0.250A - 5A
	29862	0.250A - 5A

Additional Information



Datasheet



Resources



Samples

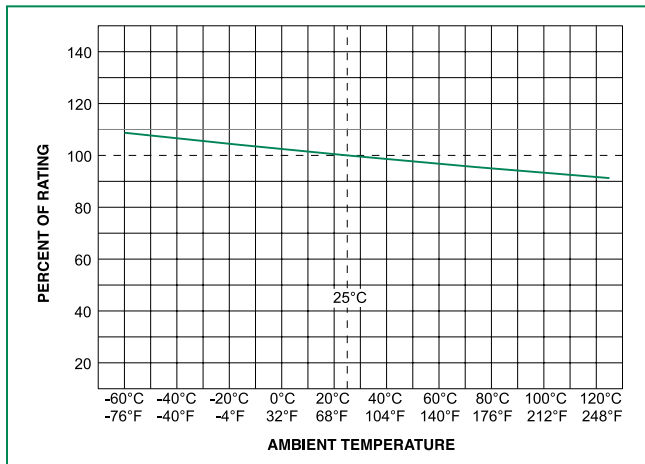
Electrical Characteristics for Series

% of Ampere Rating	Opening Time
100%	4 hours, Minimum
200%	1 second, Min; 30 seconds Max.

Electrical Specifications by Item

Ampere Rating (A)	Amp Code	Max Voltage Rating (V)	Interrupting Rating	Nominal Cold Resistance (Ohms)	Nominal Melting I ² t (A ² sec)	Agency Approvals	
0.25	.250	250	50A@250VAC	1.320	0.0126	x	x
0.50	.500	250		0.433	0.112	x	x
0.75	.750	250		0.158	0.462	x	x
1.00	001.	250		0.0755	0.328	x	x
1.50	015.	250		0.0399	0.850	x	x
2.00	002.	250		0.0337	1.70	x	x
2.50	02.5	250		0.0243	2.87	x	x
3.00	003.	250		0.0197	4.40	x	x
4.00	004.	250		0.0148	11.66	x	x
5.00	005.	250		0.0120	14.7	x	x

Temperature Re-rating Curve



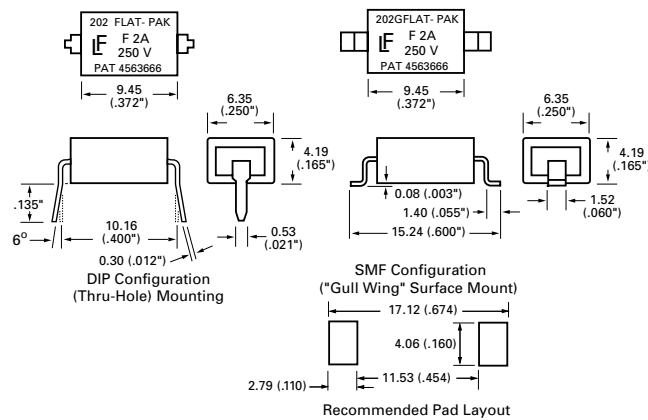
Note:

1. Re-rating depicted in this curve is in addition to the standard derating of 25% for continuous operation.

Soldering Parameters

Wave Soldering	260°C, 3 seconds max.
Reflow Soldering	215°C, 30 seconds max.

Dimensions



Packaging

Packaging Option	Packaging Specification	Quantity	Quantity & Packaging Code
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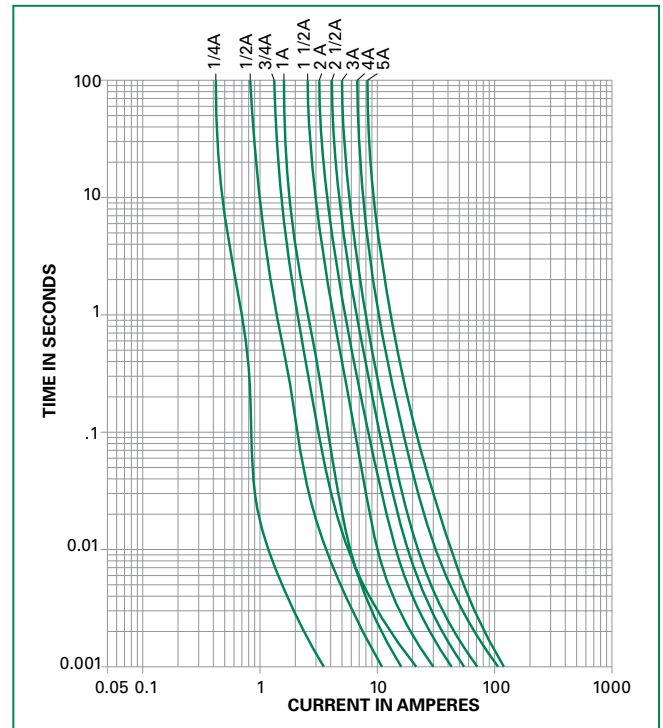
Surface Mount Fuses

Bulk	-	100	HXG
24mm Tape and Reel	EIA 481 (IEC60286, part 3)	500	URG

Through Hole Fuses

Antistatic Magazine	-	100	H
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Average Time Current Curves



Product Characteristics

Materials	Body: Thermoplastic Terminations: Tin/Lead Plated Copper
Solderability	MIL-STD-202, Method 208.
Cleaning	Board washable in most common solvents.
Operating Temperature	-55°C to 125°C

Part Numbering System

Surface Mount Fuses:

0203 002. HXG

Series

Amp Code

Refer to Amp Code column of Electrical Characteristics Table

Quantity Code

HXG = 100
URG = 500

Through Hole Fuses:

0203 002. H

Series

Amp Code

Refer to Amp Code column of Electrical Characteristics Table

Quantity Code

H = 100